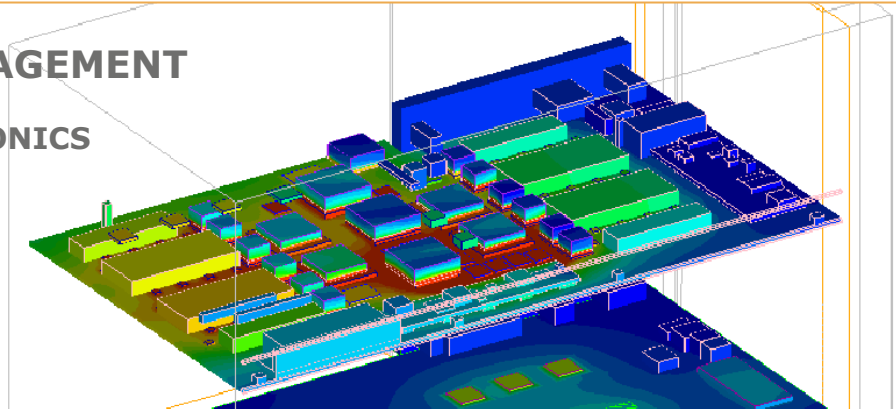


## THERMAL MANAGEMENT IN POWER ELECTRONICS



### Temperature is a common cause of failure of power modules.

Therefore, thermal management and electronic design are becoming more crucial for planning and development processes of electronic systems.

In order to ensure optimal heat dissipation, the correct choice and practice-oriented usage of climate control components are necessary.

Testing and optimization of cooling components, units, and systems in power electronics are performed by analyzing flow and temperature conditions. For example for

- fans,
- heat sinks,
- circuit boards,
- frequency converters,
- power supplies,
- etc.

The inclusion and analysis of thermal management is also important for component cooling and fan management. Thus, the determination of flow and temperature conditions, and the analysis of the usage of different fan types, can give information about boundary conditions and thermal data for the system integration.

